

*Sub B2*

12. (Amended) A method of forming a solder ball contact, comprising:  
    forming a metal contact pad on a substrate;  
    forming an insulating layer on the metal contact pad;  
    removing a portion of the insulating layer to expose a portion of the metal contact pad, thereby forming an exposed portion of the metal contact pad, the exposed portion having a predetermined diameter;  
    adsorbing reactants on the exposed portion of the metal contact pad;  
    reacting the reactants on the exposed portion of the metal contact pad, thereby forming a solder contact; and  
    annealing the solder contact to form a solder ball contact.

*02*

13. (Amended) A method of forming a solder ball contact, comprising:  
    forming a metal contact pad on a substrate;  
    forming an insulating layer on the metal contact pad;  
    forming a resist layer on the insulating layer;  
     patterning the resist layer to define a future exposed portion of the metal contact pad;  
    removing a portion of the insulating layer to expose a portion of the metal contact pad, thereby forming the exposed portion of the metal contact pad, the exposed portion having a predetermined diameter;  
    electrolytically depositing solder on the exposed portion of the metal contact pad, thereby forming a solder contact;  
    removing the resist layer, thereby exposing the solder contact above a surface of the insulating layer; and  
    annealing the solder contact to form a solder ball contact.

*Sub B3*  
*03*  
*Cont.*

16. (Amended) A method of forming a solder ball contact, comprising:  
    forming a metal contact pad on a substrate;  
    forming an insulating layer on the metal contact pad;  
    forming a resist layer on the insulating layer;  
    patterning the resist layer to define a future exposed portion of the metal contact pad;